

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

Claims 1-8 (Canceled).

Claim 9 (Currently Amended): A device used to produce or examine semiconductors comprising:

a ceramic substrate having a ~~conductor layer~~ resistance heating element formed on the surface thereof ~~or inside thereof~~; and

a supporting case~~[[;]]~~, wherein

an external terminal is connected to said ~~conductor layer~~ resistance heating element,  
and

said external terminal is pressed on said ~~conductor layer~~ resistance heating element, or  
said external terminal is pressed on ~~another~~ a conductor layer connected to said ~~conductor layer~~ resistance heating element.

Claim 10 (Currently Amended): The device used to produce or examine semiconductors according to claim 9, ~~wherein said device comprises~~ further comprising:

an elastic body, ~~and wherein~~

elasticity of said elastic body is used to connect said external terminal and said ~~conductor layer~~ resistance heating element, or to connect said external terminal and said ~~another~~ conductor layer.

Claims 11-16 (Canceled).

Claim 17 (New): The device used to produce or examine semiconductors according to claim 9, wherein said resistance heating element comprises:

two or more circuits.

Claim 18 (New): The device used to produce or examine semiconductors according to claim 9, wherein said resistance heating element comprises:

a metal particle; and

a metal oxide.

Claim 19 (New): The device used to produce or examine semiconductors according to claim 9, further comprising:

a heat insulating ring, wherein

said ceramic substrate is fixed to said supporting case interposing said heat insulating ring between said ceramic substrate and said supporting case.

Claim 20 (New): The device used to produce or examine semiconductors according to claim 9, wherein said ceramic substrate comprises:

a through hole for inserting a lifter pin.

Claim 21 (New): A device used to produce or examine semiconductors, comprising:

a ceramic substrate having a resistance heating element formed inside thereof;

a supporting case; and

an external terminal connected to said resistance heating element, wherein

said external terminal is pressed on said resistance heating element, or said external terminal is pressed on a conductor layer connected to said resistance heating element.

Claim 22 (New): The device used to produce or examine semiconductors according to claim 21, further comprising:

an elastic body, wherein

elasticity of said elastic body is used to connect said external terminal and said resistance heating element, or to connect said external terminal and said conductor layer.

Claim 23 (New): The device used to produce or examine semiconductors according to claim 21, wherein said resistance heating element comprises:

two or more circuits.

Claim 24 (New): The device used to produce or examine semiconductors according to claim 21, wherein said ceramic substrate comprises:

a through hole for inserting a lifter pin.